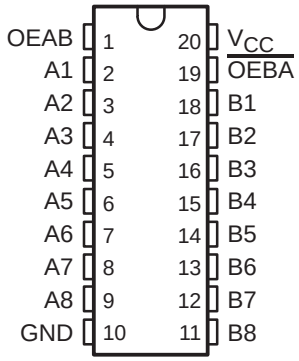
- **Local Bus-Latch Capability**
- **Choice of True or Inverting Logic**
- **Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs**

DEVICE	OUTPUT	LOGIC
SN74ALS620A	3 state	Inverting
SN74ALS621A	Open collector	True
SN74ALS623A, SN74AS623	3 state	True

DW OR N PACKAGE
(TOP VIEW)



description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the output-enable (OEAB and $\overline{\text{OEBA}}$) inputs.

The output-enable inputs disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability to store data by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. Each output reinforces its input in this transceiver configuration. When both OEAB and $\overline{\text{OEBA}}$ are enabled and all other data sources to the two sets of bus lines are in the high-impedance state, both sets of bus lines (16 total) remain at their last states. The 8-bit codes appearing on the two sets of buses are identical for the SN74ALS621A, SN74ALS623A, and SN74AS623 or complementary for the SN74ALS620A.

The -1 versions of the SN74ALS620A and SN74ALS621A are identical to the standard versions, except that the recommended maximum I_{OL} is increased to 48 mA in the -1 versions.

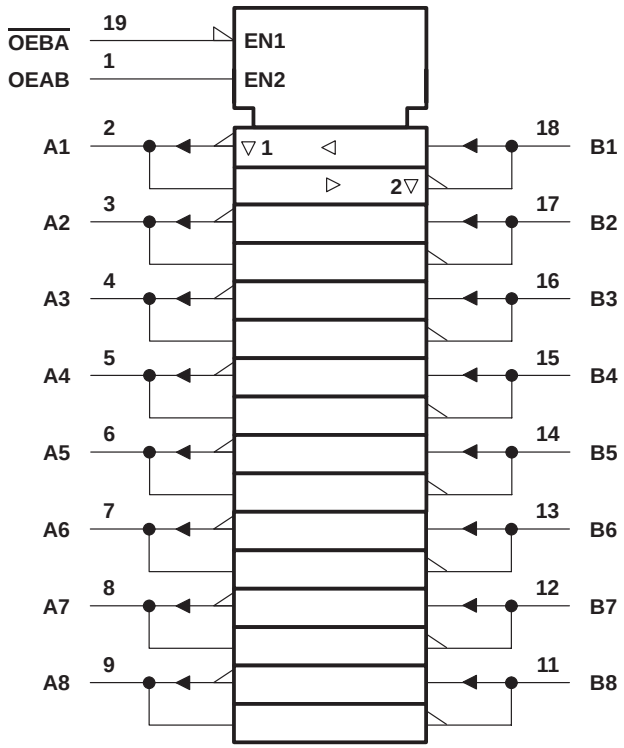
The SN74ALS620A, SN74ALS621A, SN74ALS623A, and SN74AS623 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE

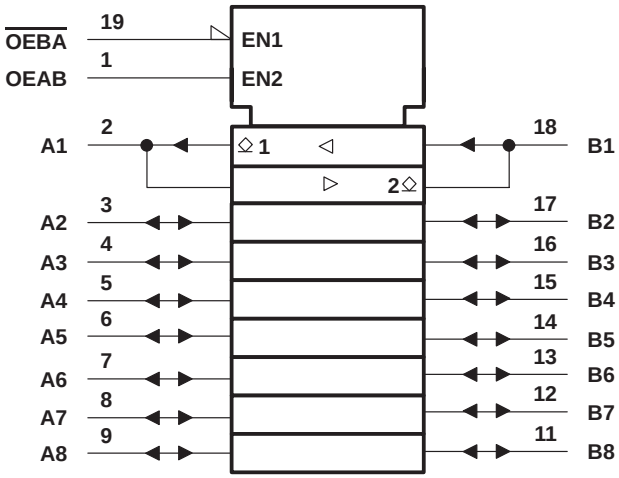
INPUTS		OPERATION	
$\overline{\text{OEBA}}$	OEAB	SN74ALS620A	SN74ALS621A SN74ALS623A SN74AS623
L	L	$\overline{\text{B}}$ data to A bus	B data to A bus
H	H	$\overline{\text{A}}$ data to B bus	A data to B bus
H	L	Isolation	Isolation
L	H	$\overline{\text{B}}$ data to A bus, $\overline{\text{A}}$ data to B bus	B data to A bus, A data to B bus

logic symbols†

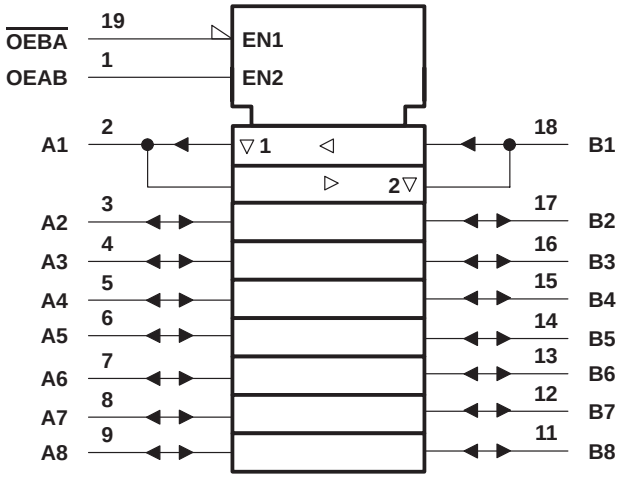
SN74ALS620A



SN74ALS621A



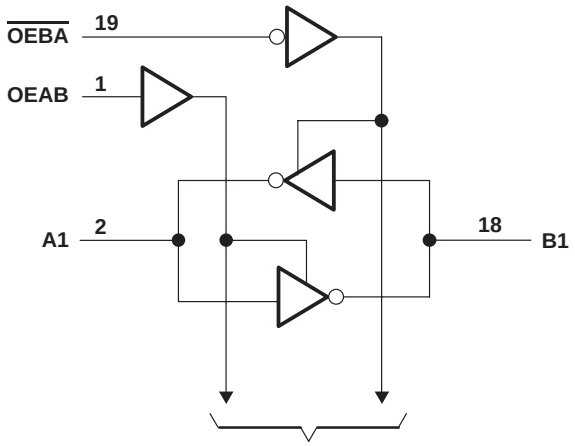
SN74ALS623A, SN74AS623



† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

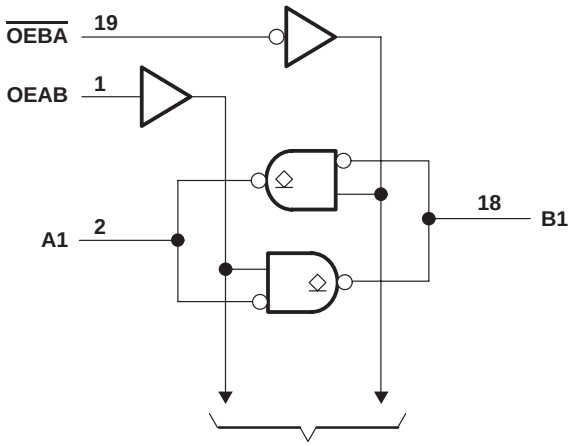
logic diagrams (positive logic)

SN74ALS620A



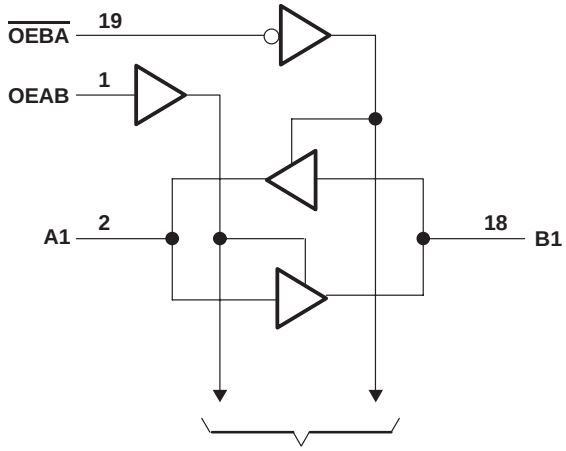
To Seven Other Transceivers

SN74ALS621A



To Seven Other Transceivers

SN74ALS623A, SN74AS623



To Seven Other Transceivers

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I: All inputs	7 V
I/O ports	5.5 V
Operating free-air temperature range, T_A: SN74ALS620A, SN74ALS623A	0°C to 70°C
Storage temperature range	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN74ALS620A SN74ALS623A			UNIT
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			–15	mA
I_{OL}	Low-level output current			24	mA
T_A	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN74ALS620A SN74ALS623A			UNIT
				MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2	V
V_{OH}		V_{CC} = 4.5 V to 5.5 V,	I_{OH} = –0.4 mA	V_{CC} –2			V
		V_{CC} = 4.5 V	I_{OH} = –3 mA	2.4	3.2		
			I_{OH} = –15 mA	2			
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 12 mA		0.25	0.4	V
			I_{OL} = 24 mA‡		0.35	0.5	
I_I	Control inputs	V_{CC} = 5.5 V	V_I = 7 V			0.1	mA
	A or B ports		V_I = 5.5 V			0.1	
I_{IH}	Control inputs	V_{CC} = 5.5 V,	V_I = 2.7 V			20	µA
	A or B ports§					20	
I_{IL}	Control inputs	V_{CC} = 5.5 V,	V_I = 0.4 V			–0.1	mA
	A or B ports§					–0.1	
I_O¶		V_{CC} = 5.5 V,	V_O = 2.25 V	–30		–112	mA
I_{CC}	SN74ALS620A	V_{CC} = 5.5 V	Outputs high		24	34	mA
			Outputs low		31	44	
			Outputs disabled		33	47	
	SN74ALS623A	V_{CC} = 5.5 V	Outputs high		32	43	
			Outputs low		39	50	
			Outputs disabled		42	55	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V
§ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
¶ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX†				UNIT
			SN74ALS620A		SN74ALS623A		
			MIN	MAX	MIN	MAX	
t_{PLH}	A	B	2	10	2	13	ns
t_{PHL}			2	10	3	11	
t_{PLH}	B	A	2	10	2	13	ns
t_{PHL}			2	10	3	11	
t_{PZH}	$\overline{OEBA}$	A	3	17	5	22	ns
t_{PZL}			5	25	5	22	
t_{PHZ}	$\overline{OEBA}$	A	2	12	2	16	ns
t_{PLZ}			3	18	2	19	
t_{PZH}	OEAB	B	3	18	5	22	ns
t_{PZL}			5	25	5	22	
t_{PHZ}	OEAB	B	2	12	2	16	ns
t_{PLZ}			3	18	2	19	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC} . . . . . 7 V
Input voltage, V_I: All inputs and I/O ports . . . . . 7 V
Operating free-air temperature range, T_A: SN74ALS621A . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN74ALS621A			UNIT
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_{OH}	High-level output voltage			5.5	V
I_{OL}	Low-level output current			24	mA
				48§	mA
T_A	Operating free-air temperature	0		70	°C

§ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN74ALS621A			UNIT
				MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.5	V
I_{OH}		V_{CC} = 4.5 V,	V_{OH} = 5.5 V			0.1	mA
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 24 mA		0.35	0.5	V
			I_{OL} = 48 mA‡		0.35	0.5	
I_I	Control inputs	V_{CC} = 5.5 V	V_I = 7 V			0.1	mA
	A or B ports		V_I = 5.5 V			0.1	
I_{IH}	Control inputs	V_{CC} = 5.5 V,	V_I = 2.7 V			20	µA
	A or B ports§					20	
I_{IL}	Control inputs	V_{CC} = 5.5 V,	V_I = 0.4 V			–0.1	mA
	A or B ports§					–0.1	
I_{CC}		V_{CC} = 5.5 V	Outputs high		29	40	mA
			Outputs low		35	48	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V
§ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 680 Ω, T_A = MIN to MAX¶		UNIT
			SN74ALS621A		
			MIN	MAX	
t_{PLH}	A	B	10	33	ns
t_{PHL}			5	20	
t_{PLH}	B	A	10	33	ns
t_{PHL}			5	20	
t_{PLH}	$\overline{OEBA}$	A	10	39	ns
t_{PHL}			12	35	
t_{PLH}	OEAB	B	10	39	ns
t_{PHL}			12	35	

¶ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} . . . . . 7 V
Input voltage, V_I: All inputs . . . . . 7 V
I/O ports . . . . . 5.5 V
Operating free-air temperature range, T_A: SN74AS623 . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN74AS623			UNIT
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			–15	mA
I_{OL}	Low-level output current			64	mA
T_A	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN74AS623			UNIT
				MIN	TYP‡	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2	V
V_{OH}		V_{CC} = 4.5 V to 5.5 V,	I_{OH} = –2 mA	V_{CC} –2			V
		V_{CC} = 4.5 V	I_{OH} = –3 mA	2.4	3.2		
			I_{OH} = –15 mA	2			
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 64 mA		0.35	0.55	V
I_I	Control inputs	V_{CC} = 5.5 V	V_I = 7 V			0.1	mA
	A or B ports		V_I = 5.5 V			0.1	
I_{IH}	Control inputs	V_{CC} = 5.5 V,	V_I = 2.7 V			20	µA
	A or B ports§					70	
I_{IL}	Control inputs	V_{CC} = 5.5 V,	V_I = 0.4 V			–0.5	mA
	A or B ports§					–0.75	
I_O¶		V_{CC} = 5.5 V,	V_O = 2.25 V	–30		–150	mA
I_{CC}		V_{CC} = 5.5 V	Outputs high		57	93	mA
			Outputs low		16	189	
			Outputs disabled		71	116	

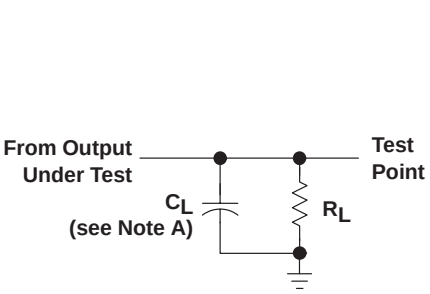
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
¶ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

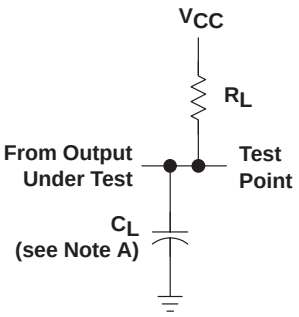
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX†		UNIT
			SN74AS623		
			MIN	MAX	
t_{PLH}	A	B	1	9	ns
t_{PHL}			1	8	
t_{PLH}	B	A	1	9	ns
t_{PHL}			1	8.5	
t_{PZH}	$\overline{OEBA}$	A	2	11	ns
t_{PZL}			2	10	
t_{PHZ}	$\overline{OEBA}$	A	1	7.5	ns
t_{PLZ}			1	11.5	
t_{PZH}	OEAB	B	2	11.5	ns
t_{PZL}			2	11	
t_{PHZ}	OEAB	B	1	7	ns
t_{PLZ}			1	9	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

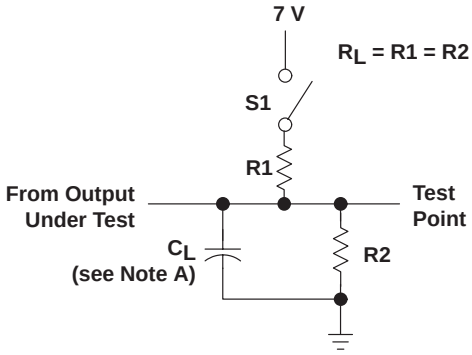
PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



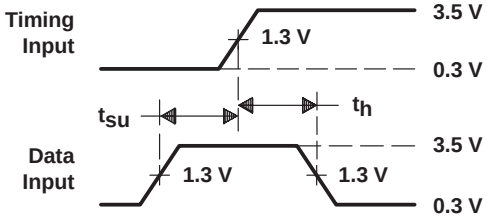
LOAD CIRCUIT FOR
BI-STATE
TOTEM-POLE OUTPUTS



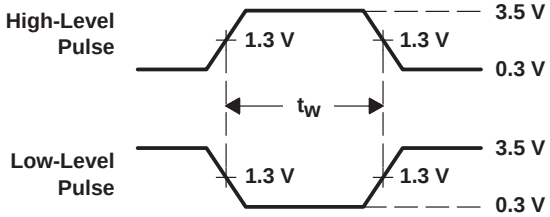
LOAD CIRCUIT
FOR OPEN-COLLECTOR OUTPUTS



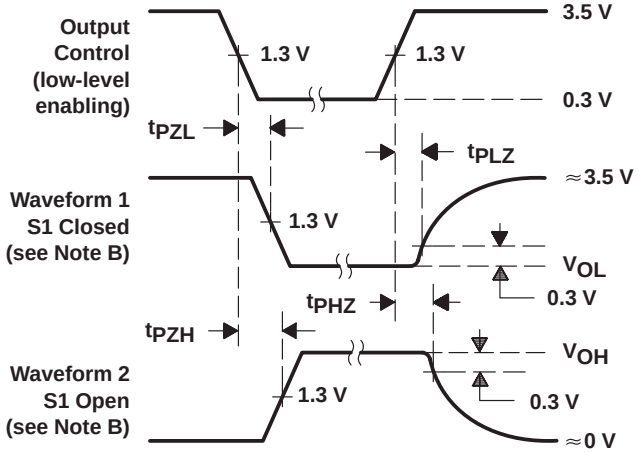
LOAD CIRCUIT
FOR 3-STATE OUTPUTS



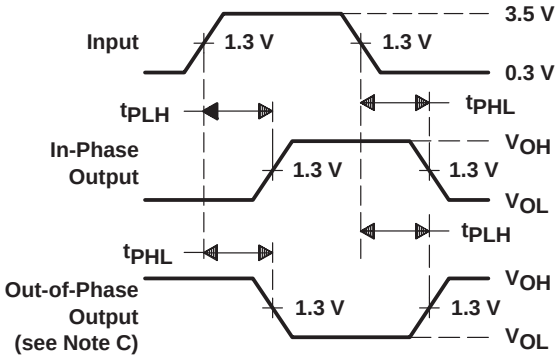
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: PRR ≤ 1 MHz, $t_r = t_f$ = 2 ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS620ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS620A	Samples
SN74ALS620ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS620A	Samples
SN74ALS620AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS620AN	Samples
SN74ALS621A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS621A-1N	Samples
SN74ALS621ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS621A	Samples
SN74ALS621ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS621A	Samples
SN74ALS621AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS621AN	Samples
SN74ALS621ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS621AN	Samples
SN74ALS623ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS623A	Samples
SN74ALS623AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS623AN	Samples
SN74ALS623ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS623A	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

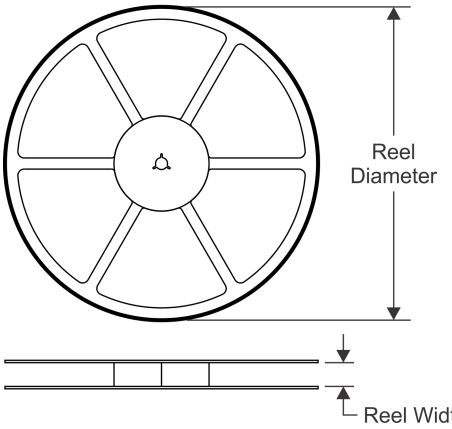
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

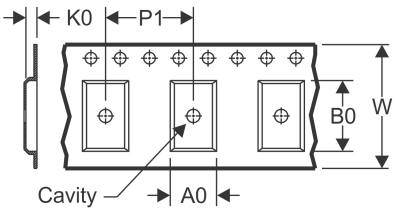
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

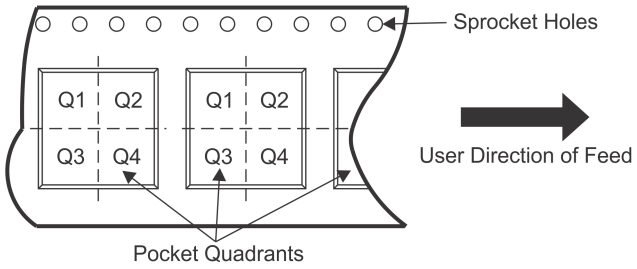


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

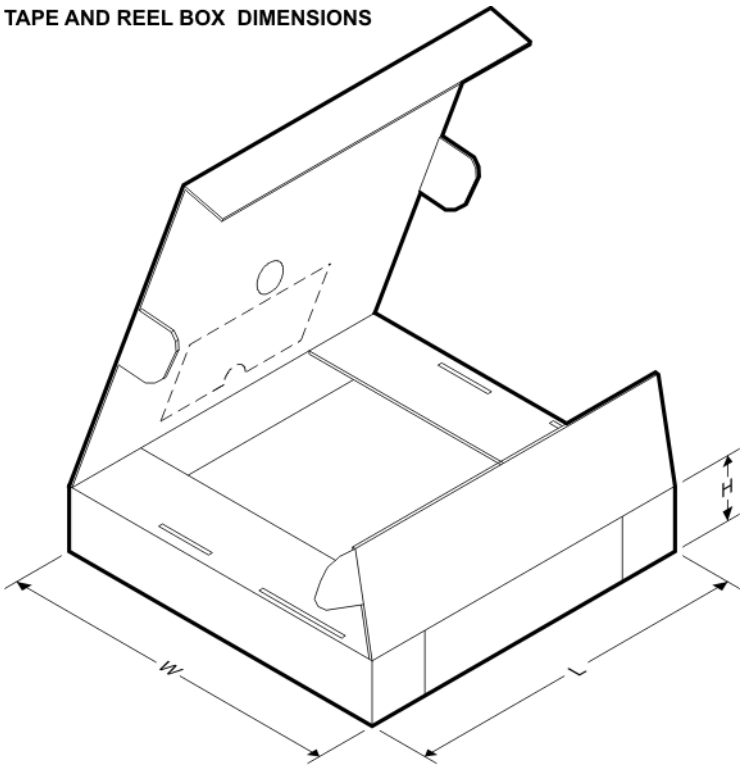
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS623ANSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



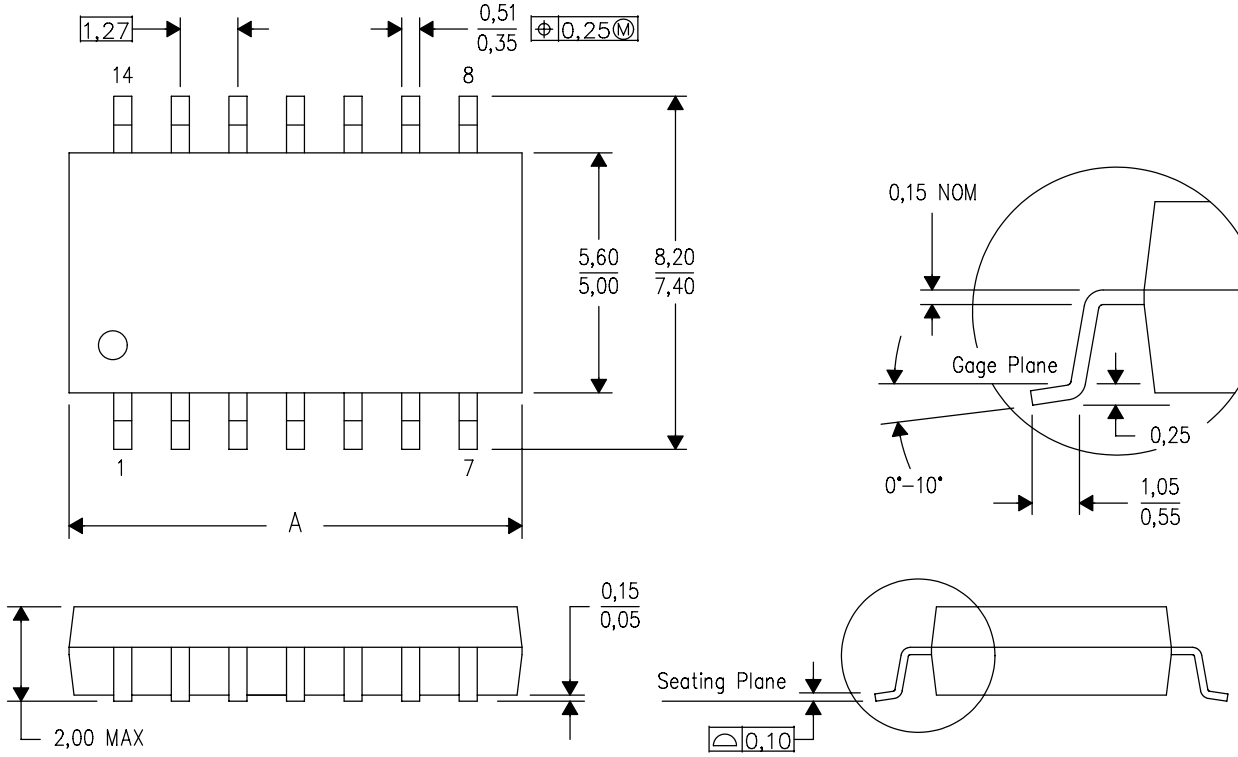
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS623ANSR	SO	NS	20	2000	367.0	367.0	45.0

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

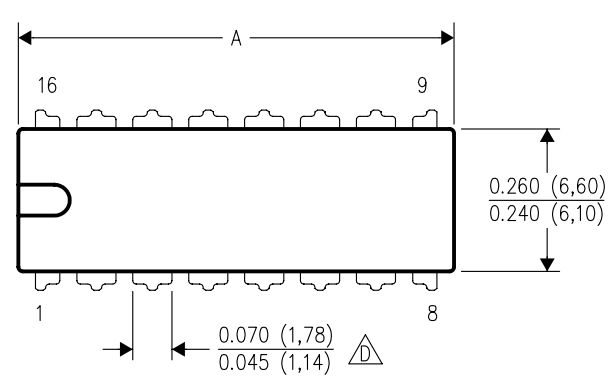
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

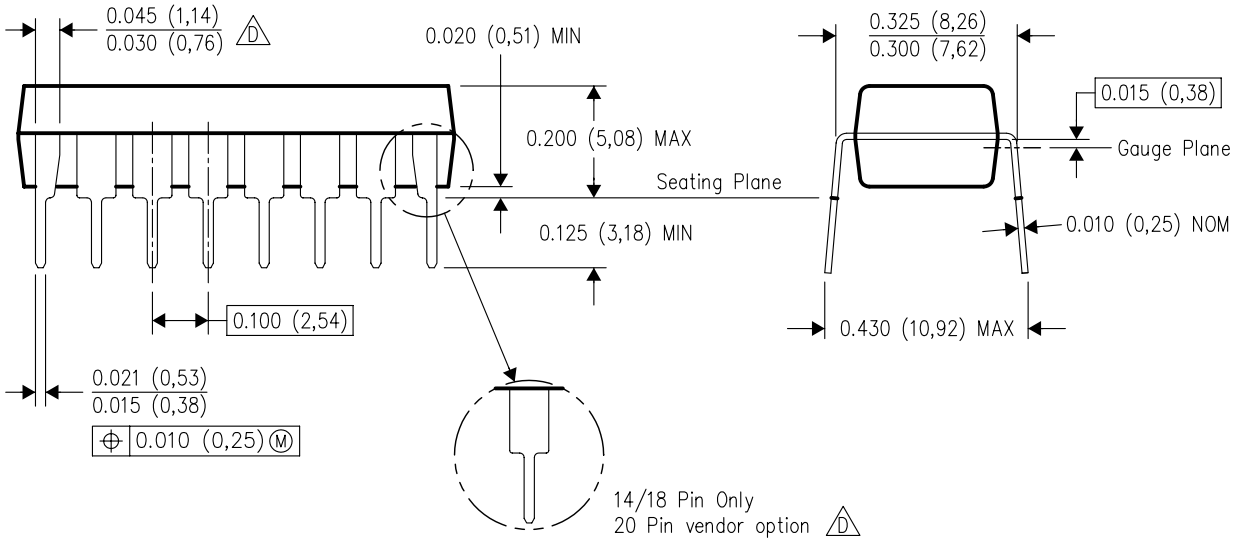
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

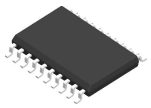


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

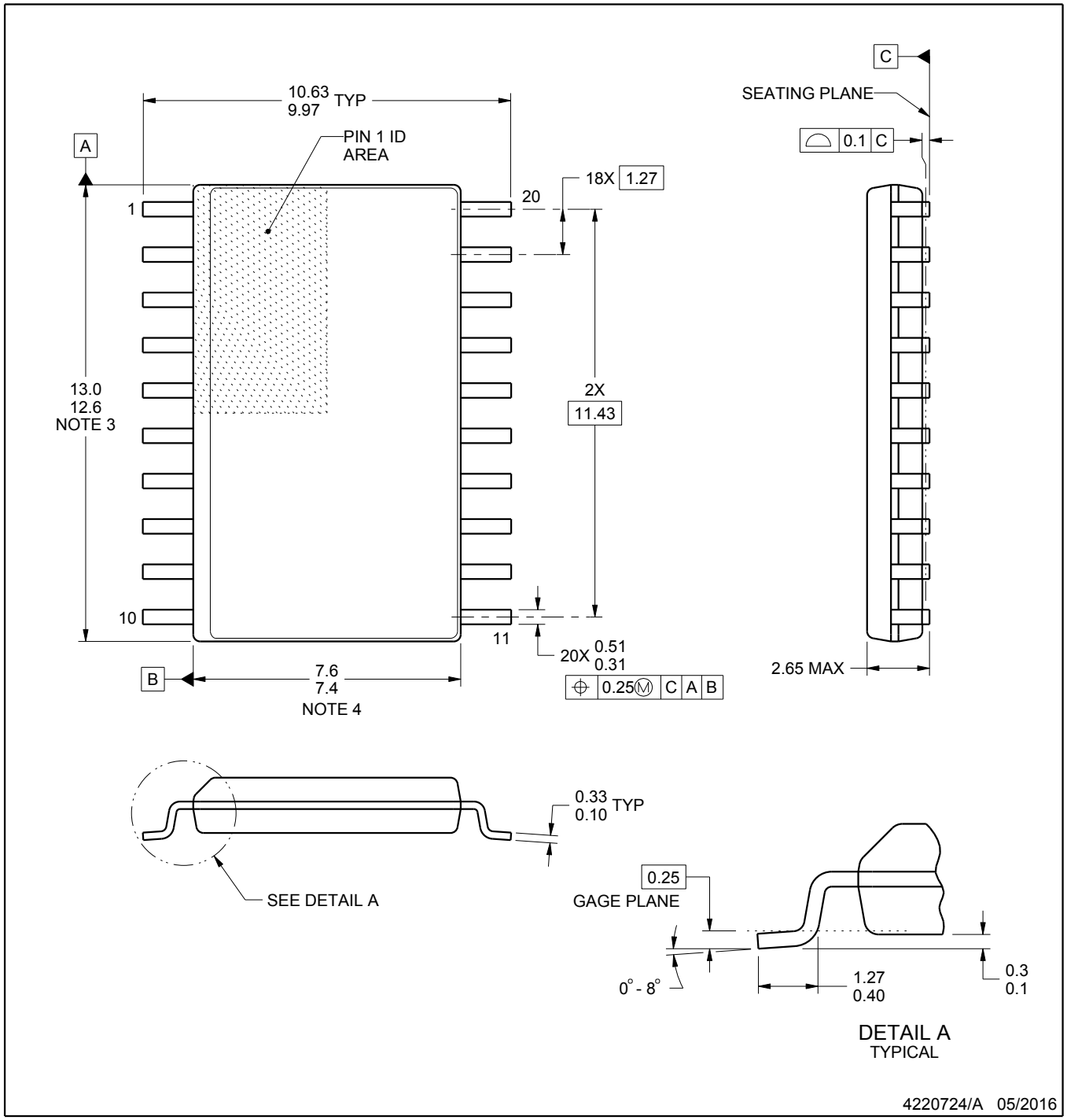


PACKAGE OUTLINE

DW0020A

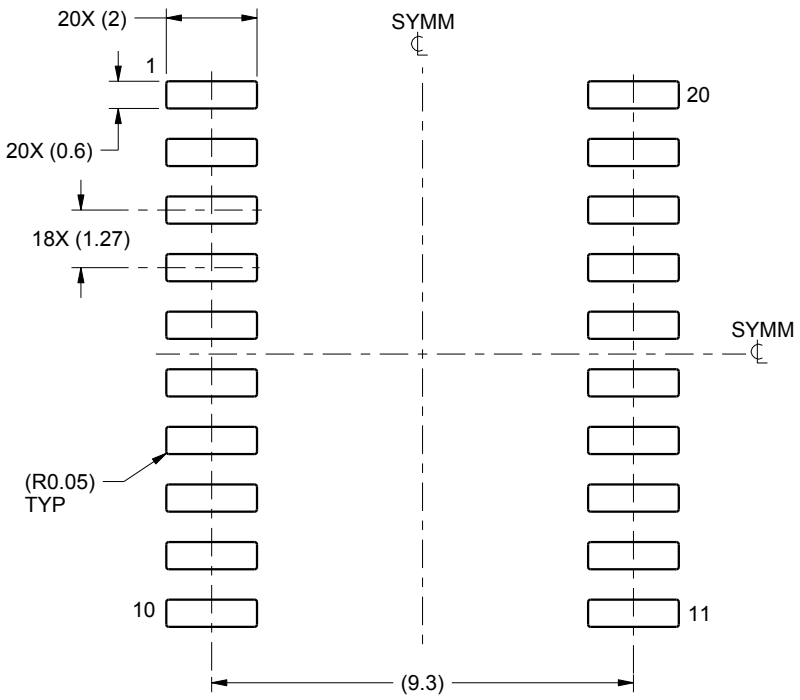
SOIC - 2.65 mm max height

SOIC

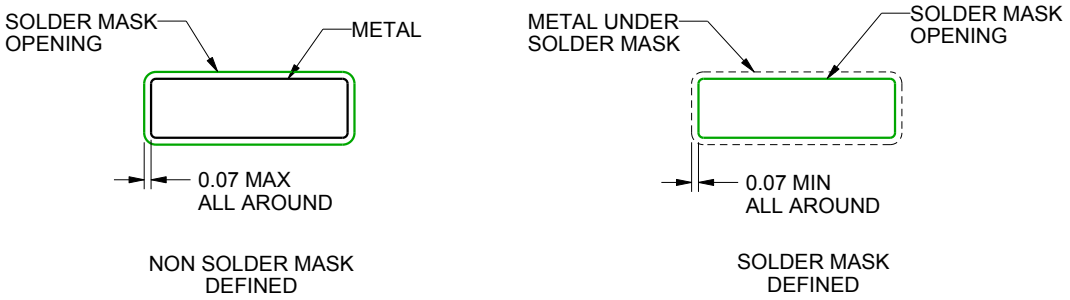


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

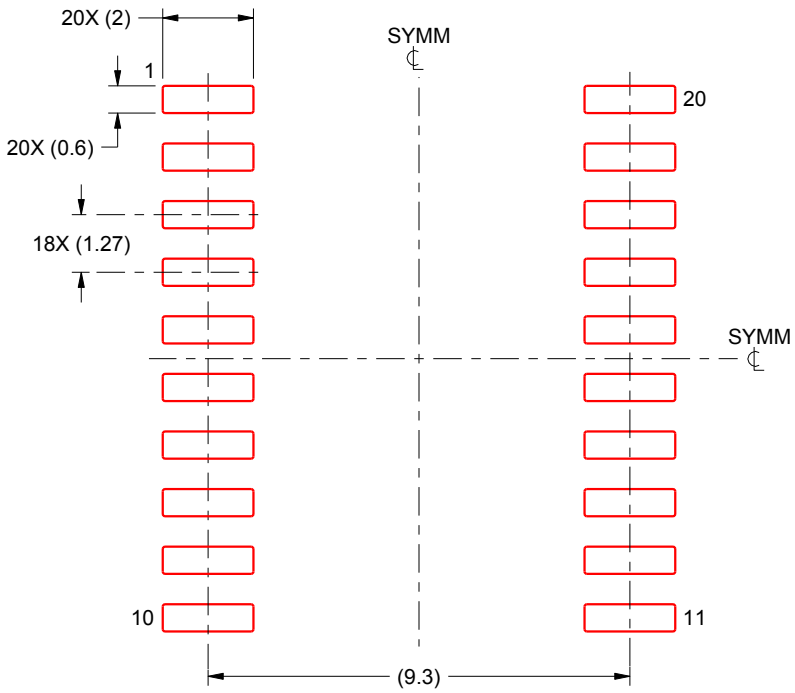


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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